

9-18-07	Application Number		10522262	
	Filing Date		2003-07-18	
	First Named Inventor		Iiro Mietanen	
	Art Unit		2811 2815	
	Examiner Name		To Be Assigned shingleton	
	Attorney Docket Number		800186US	

U.S.PATENTS						
Examiner Initial*	Cite No	Patent Number	Kind Code†	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
/MBS/1		4227942		1980-10-14	Hall	
/MBS/2		4626613		1986-12-02	Wenham et al.	
/MBS/3		4984358		1991-01-15	Nelson	
/MBS/4		5468852		1995-11-21	Gee	
5/MBS/		6836020		2004-12-28	Cheng et al.	

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FOREIGN PATENT DOCUMENTS

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Examiner Initials*	Cite No	Foreign Document Number ³	Country Code ² i	Kind Code ⁴	Publication Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear	T5
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NON-PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, pages(s), volume-issue number(s), publisher, city and/or country where published.	T5
/MBS/ 1		E.M. CHOW ET AL. "Electrical Through-Wafer Interconnects and Microfabricated Cantilever Arrays Using Through-Wafer Silicon Etching." Thesis at Stanford University, August 2001, 196 pages.	<input type="checkbox"/>
/MBS/ 2		E.M. CHOW ET AL., "Process Compatible Polysilicon-Based Electrical Through-Wafer Interconnects in Silicon Substrates," Journal of Microelectromechanical Systems, December 2002,pp. 631-640, Vol. 11, No. 6, IEEE.	<input type="checkbox"/>
/MBS/ 3		C.H. CHENG ET AL., "An Efficient Electrical Addressing Method Using Through-Wafer Vias for Two-Dimensional Ultrasonic Arrays," IEEE Ultrasonics Symposium, 2000, pp. 1179-1182.	<input type="checkbox"/>
/MBS/ 4		C.H. CHENG ET AL., "Electrical Through-Wafer Interconnects with Sub-PicoFarad Parasitic Capacitance," IEEE Microelectromechanical Systems Conference, 2002, pp. 18-21.	<input type="checkbox"/>
/MBS/ 5		V. CHANDRASEKARAN ET AL., "Through-Wafer Electrical Interconnects for MEMS Sensors," Proceedings of ASME International Mechanical Engineering Congress and Exposition, November 2001,pp. 1-6.	<input type="checkbox"/>

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EXAMINER SIGNATURE

Examiner Signature	/Michael B Shingleton/	Date Considered	4-15-2009
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Examiner Name	To Be Assigned
Attorney Docket Number	800188US

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- That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement. See 37 CFR 1.97(e)(1).

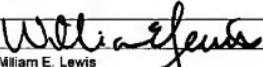
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- That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement. See 37 CFR 1.97(e)(2).

- See attached certification statement.
 Fee set forth in 37 CFR 1.17 (p) has been submitted herewith.
 None

SIGNATURE

A signature of the applicant or representative is required in accordance with CFR 1.33, 10.18. Please see CFR 1.4(d) for the form of the signature.

Signature		Date (YYYY-MM-DD)	2006-12-04
Name/Print	William E. Lewis	Registration Number	39,274

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